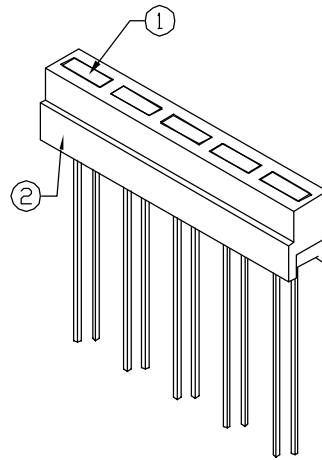
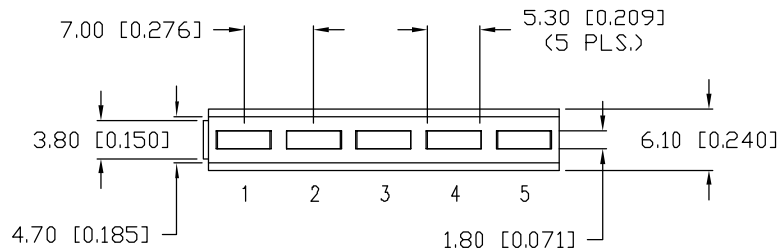


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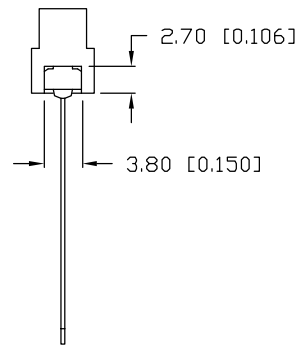
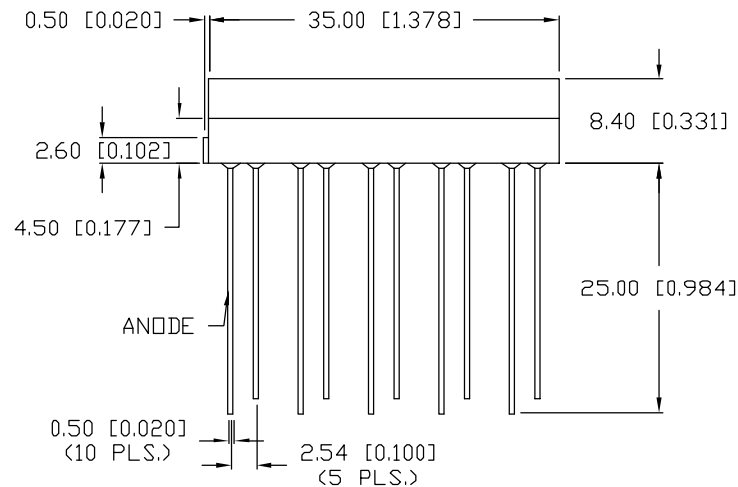
REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	6.4.01



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	RED	GREEN	UNITS	TEST COND
PEAK WAVELENGTH	635	565	nm	
FORWARD VOLTAGE (TYP.)	2.0	2.1	V_f	
FORWARD VOLTAGE (MAX.)	2.5	2.5	V_f	
REVERSE VOLTAGE	5.0	5.0	V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY	12	10	mcd	$I_f=20\text{mA}$
VIEWING ANGLE	110	110	2x theta	
LED POSITION:	1 & 5	2~4		
EPOXY LENS FINISH: DIFFUSED SAME AS EMITTED COLOR				



LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT	(R/G)	30/25	mA
POWER DISSIPATION		105	mW
DERATE FROM 25°C		-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.		-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.		+260	$^\circ\text{C}$
2.0mm FROM BODY			3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX2583GD, LED. (3 PCS.)
SSL-LX2583ID, LED. (2 PCS.)
2. SSH-LXH525, HOLDER.
3. BACKFILL BOTTOM OF HOLDER WITH U.V. GLUE TO SECURE LEADS.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

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REV.
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1.8mm x 5.3mm 5 UNIT LED ARRAY,
POS.1 & 5: RED, POS.2~4: GREEN,
COLOR DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 2.18.92
			PAGE: 1 OF 1
			SCALE: N/A